



MSC240HF170T2NHD

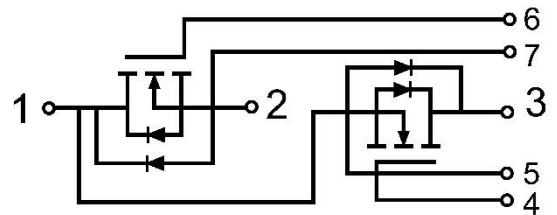
SiC MOSFET Module

Preliminary Datasheet

Features:

- SiC Power MOSFET
- Low $R_{DS(on)}$
- Low Inductance Case Avoid Oscillations
- Isolated Heatsink Using DBC Technology

Circuit Diagram



Applications:

- Main and Auxiliary AC Drives of Electric Vehicles
- DC Servo and Robot Drives
- Battery Vehicles
- UPS Equipment
- Plasma Cutting

SiC MOSFET

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Description		Values	Units
V_{DS}	Drain-Source Blocking Voltage		1700	V
V_{GSmax}	Gate-Source Voltage	Absolute Maximum Values	-10/+23	V
V_{GSop}		Recommended Operational Values	-5/+18	V
I_D	Continuous Drain Current	$V_{GS}=18\text{V}, T_C=25^{\circ}\text{C}$	240	A
		$V_{GS}=18\text{V}, T_C=100^{\circ}\text{C}$	168	A
$I_{D(pulse)}$	Pulsed Drain Current	Pulse width t_p limited by T_{Jmax}	600	A
P_D	Power Dissipation	$T_C=25^{\circ}\text{C}, T_J=175^{\circ}\text{C}$	1419	W



Electrical Characteristics of MOSFET ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Description	Conditions		Min.	Typ.	Max.	Units
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =400μA		1700			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =67mA, T _J =25℃		1.9		4.0	V
		V _{DS} =V _{GS} , I _D =67mA, T _J =175℃			2.0		
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =1700V, V _{GS} =0V, T _J =25℃				1	mA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =23V, V _{DS} =0V				400	nA
		V _{GS} =-10V, V _{DS} =0V				-400	nA
R _{DS(on)}	On State Resistance	V _{GS} =18V, I _{DS} =160A, T _J =25℃			10.0	14.0	mΩ
		V _{GS} =18V, I _{DS} =160A, T _J =175℃			21.3		
g _{fs}	Transconductance	V _{DS} =20V, I _{DS} =160A, T _J =25℃			106.8		S
		V _{DS} =20V, I _{DS} =160A, T _J =175℃			92		S
C _{iss}	Input Capacitance	V _{DS} =1000V, f=1MHz, V _{GS} =0V, V _{AC} =25mV			11.36		nF
C _{oss}	Output Capacitance				0.41		
C _{rss}	Reverse Transfer Capacitance				0.03		
E _{oss}	C _{oss} Stored Energy				201.6		μJ
Q _G	Total Gate Charge	V _{DS} =800V, V _{GS} =-5V/+18V, I _D =160A			568		nC
Q _{GS}	Gate-Source Charge				152		nC
Q _{GD}	Gate-Drain Charge				224		nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =800V, V _{GS} =-5V/+18V, I _D =160A, R _G =0.6Ω	T _J =25℃		19		ns
t _r	Rise Time		T _J =25℃		31		ns
t _{d(off)}	Turn-off Delay Time		T _J =25℃		52		ns
t _f	Fall Time		T _J =25℃		14		ns
E _{on}	Turn-on Switching Energy		T _J =25℃		2.48		mJ
E _{off}	Turn-off Switching Energy		T _J =25℃		2.80		mJ
R _{G(int)}	Internal Gate Resistance				2.2		Ω
R _{θJC}	Thermal Resistance Junction-to-Case (per SiC MOSFET)					0.106	℃/W



Reverse SiC Diode

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

V_{RRM}	Repetitive Peak Reverse Voltage		1700	V
I_F	Continuous Forward Current	$T_C=175^{\circ}\text{C}$	200	A
I_{FSM}	Non-repetitive Peak Forward Surge Current, Half Sine Wave	$T_C=25^{\circ}\text{C}$, $t_p=8.3\text{ms}$	2000	A
I^2t	I^2t - value	$T_C=25^{\circ}\text{C}$, $t_p=8.3\text{ms}$	20000	A^2s

Electrical Characteristics of Diode ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Description	Conditions		Min.	Typ.	Max.	Units
V _F	Forward Voltage	I _F =200A	T _J =25℃		1.45	1.70	V
			T _J =175℃		2.15		V
I _R	Reverse Current	V _R =1700V, T _J =25℃				1	mA
		V _R =1700V, T _J =175℃				10	mA
Q _C	Total Capacitive Charge	V _R =800V, I _F =200A, T _J =25℃			1280		nC
C	Total Capacitance	f=1MHz, T _J =25℃	V _R =0.1V		34.4		nF
			V _R =1000V		0.68		nF
			V _R =1700V		0.63		nF
R _{θJC}	Thermal Resistance: Junction-to-Case (per SiC Diode)					0.069	℃/W



Module

Symbol	Description	Min.	Typ.	Max.	Units
V _{iso}	Isolation Voltage (All Terminals Shorted) f=50Hz, t=1min	6800			V
Internal Isolation		AIN			
d _{creep}	Creepage Distance: Terminal to Baseplate		40		mm
	Creepage Distance: Terminal to Terminal		30		mm
d _{clear}	Clearance Distance: Terminal to Baseplate		30		mm
	Clearance Distance: Terminal to Terminal		9		mm
L _{SCE}	Stray Inductance Module			14	nH
T _J	Maximum Junction Temperature			175	°C
T _{JOP}	Maximum Operating Junction Temperature Range	-40		+175	°C
T _{stg}	Storage Temperature	-40		+125	°C
CTI	Comparative Tracking Index	200			
R _{θCS}	Case-to-Sink Thermally (Conductive Grease Applied)			0.03	°C/W
M	Power Terminals Screw:M6	3.0		5.0	N·m
M	Mounting Screw:M6	3.0		6.0	N·m
G	Weight		300		g

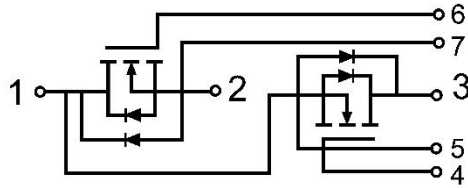
Ordering Information Table

Device code	M	SC	240	HF	170	T2N	H	D
	①	②	③	④	⑤	⑥	⑦	⑧

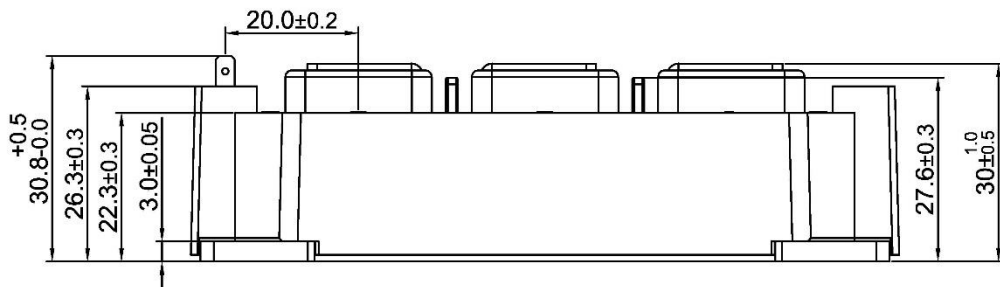
- ① - MOSFET Module
- ② - SiC MOSFET
- ③ - Rated Current (240=240A)
- ④ - Circuit Configuration (Half Bridge)
- ⑤ - Rated Voltage (170=1700V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)
- ⑧ - Internal Code



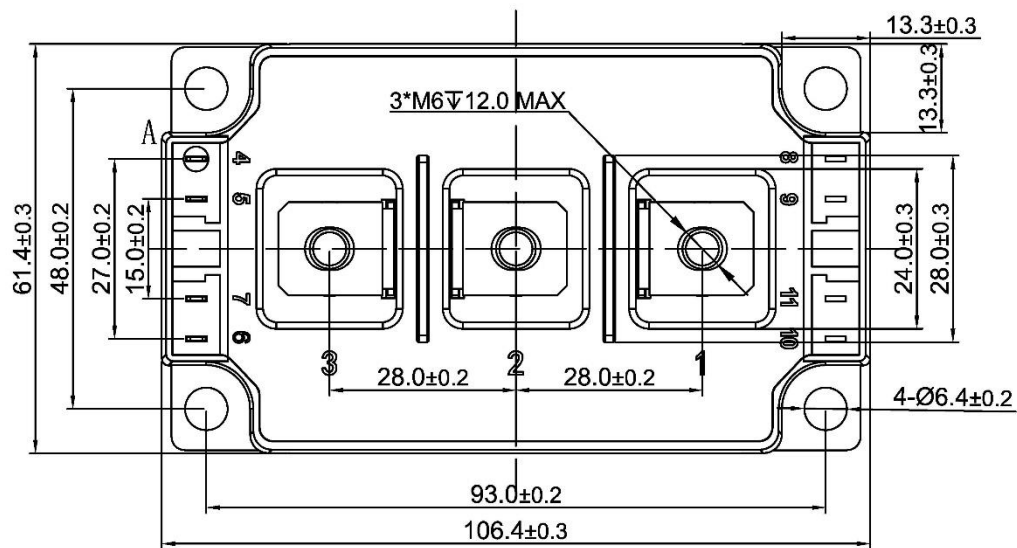
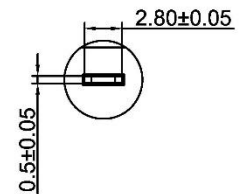
Internal Circuit:



Package Outline (Unit: mm):



View A
scale 3:1





Revision	Notes
01	Initial Release

Announcement

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The released datasheet would be issued with “REV.” + “alphabet characters”.